



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16891

Generic Copy

Issue Date: 02-Apr-2013

TITLE: Wafer Capacity Expansion for Trench 3 MOSFETs

PROPOSED FIRST SHIP DATE: 03-JUL-2013

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Wafer Fab Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or
Melyssa Hutchins<melyssa.hutchins@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or
Brian Goodburn<brian.goodburn@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or
Donna Scheuch<d.scheuch@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This Product Change Notice is to announce that ON Semiconductor is adding wafer fabrication capacity for their Trench 3 MOSFET technology silicon platforms. ON Semiconductor has qualified United Microelectronics Corp (UMC), a wafer fabrication facility located in Taiwan. Upon expiration of this FPCN, ON Semiconductor will supply parts utilizing the UMC fab. Device quality and reliability will continue to meet ON Semiconductors high standards.



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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Name	Test Conditions	Test Results	(rej/ ss)	(rej/ ss)	(rej/ ss)	(rej/ ss)
			Read Point	NTMFS4933	NTMFS4933	NTMFS4935	NTMFS4935
Prep	Sample preparation and initial part testing	various	Initial Electrical	done	done	done	done
HTRB	High Temp Reverse Bias	TA = 150°C , Vdss = 80% of max rated	504 Hrs	0/77	0/77	0/77	0/77
HTGB	High Temp Gate Bias	TA = 150°C , Vgss = 100% of max rated	504 Hrs	0/77	0/77	0/77	0/77
MSL 1 PC - IOL	Intermittent Operating Life + PC	Ta=+25°C, delta Tj=100°C On/of = 2 min	7500 Hrs	0/77	0/77	0/77	0/77
MSL 1 PC - TC	Temperature Cycling + PC	-55 °C to + 150°C	500 Cyc	0/77	0/77	0/77	0/77
MSL 1 PC - AC	Autoclave + PC	121°C/100% RH/15psig	96 Hrs	0/77	0/77	0/77	0/77
MSL 1 PC - HAST	Highly Accelerated Stress Test	Temp= +131°C, RH=85% , p = 18.8 psig, bias	96 Hrs	0/77	0/77	0/77	0/77

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in electrical parametric performance. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

There will be no physical change to the Devices assembled with Die from the United Microelectronics Corp (UMC) wafer fabrication facility. There will be Wafer Lot traceability from the manufacturing Lot to determine the Die origin.



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List of affected General Parts:

NC4901NT1G
NC4901NT3G
NC4902NT1G
NC4902NT3G
NTMFS4923NET1G
NTMFS4923NET3G
NTMFS4925NET1G
NTMFS4925NET3G
NTMFS4925NT1G
NTMFS4925NT3G
NTMFS4926NET1G
NTMFS4926NET3G
NTMFS4926NT1G
NTMFS4927NCT1G
NTMFS4927NT1G
NTMFS4927NT3G
NTMFS4931NT1G
NTMFS4931NT3G
NTMFS4933NT1G
NTMFS4935NBT1G
NTMFS4935NBT3G
NTMFS4935NCT1G
NTMFS4935NCT3G
NTMFS4935NT1G
NTMFS4935NT3G
NTMFS4936NCT1G
NTMFS4936NT1G
NTMFS4936NT3G
NTMFS4937NT1G
NTMFS4937NT3G
NTMFS4939NT1G
NTMFS4939NT3G
NTMFS4955NT1G
NTTFS4928NTAG
NTTFS4928NTWG
NTTFS4932NTAG
NTTFS4932NTWG
NTTFS4937NTAG
NTTFS4937NTWG
NTTFS4939NTAG
NTTFSC4937NTAG